

**IN THE CLAIMS**

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Please cancel claims 1-10 without prejudice or disclaimer, and substitute the following new claims:

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--11. (New) The method of reducing electromagnetic interference generated within an integrated circuit device package wherein the integrated circuit device package comprises  
a wafer having circuitry disposed thereon;  
a plurality of conductors coupled to the wafer; and  
a structure that encapsulates and supports the wafer;  
said method comprising applying a lossy magnetic material in the vicinity of at least one of the conductors to reduce electromagnetic radiation at the highest frequency signal components while introducing generally little inductance effects of overshoot and ringing associated with the series inductance of the at least one of the conductors.--

--12. (New) The method of claim 11, wherein the structure that encapsulates and supports the wafer comprises an encapsulating medium, and said method further comprises introducing lossy magnetic material into the encapsulating medium so as to cause the series inductance of the at least one of the conductors to behave as a lossy inductor so as to attenuate the highest frequency signal components while introducing generally little inductance effects of overshoot and ringing.--

--13. (New) The method of claim 12, wherein a relatively small amount of lossy magnetic material is introduced into the encapsulating medium so that the relative permeability in the vicinity of the at least one of

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the conductors is not so high as to cause significant mutual coupling with other of the plurality of conductors.--

--14. (New) The method of claim 13, where the introduction of the relatively small amount of lossy magnetic material results in a relative permittivity of the encapsulating medium in the range from about five to about ten.--

--15. (New) The method of claim 13, where the mutual inductance between the one of the plurality of conductors and an adjacent conductor is small with respect to the self-inductance of each conductor.--

--16. (New) The method of claim 11, wherein the lossy magnetic material is applied such that mutual coupling of the one of the plurality of conductors and an adjacent conductor is substantially eliminated.--

--17. (New) The method of claim 11, where the lossy magnetic material substantially surrounds the one of the plurality of conductors and effectively chokes undesired high frequency signals immediately external to the at least one of the conductors without substantially affecting data signals passing therethrough.--

--18. (New) The method of claim 17, where the structure that encapsulates and supports the wafer comprises an encapsulating medium that is substantially free of magnetic material.--

--19. (New) The method of claim 17, where the structure that encapsulates and supports the wafer comprises an encapsulating medium